Interview with FICT Limited President & CEO Takahisa Amemiya
Rapid Expansion in High-Multilayer PCB Orders
Strengthening R&D Capabilities in Nagano

April 23, 2026 | English Translation

FICT Limited (Nagano, Japan), a specialist in ultra-high multilayer printed circuit boards and large semiconductor package substrates, is experiencing strong business momentum. Strong demand from AI servers and semiconductor tester-related applications is driving growth. Looking ahead to the broader adoption of next-generation, highly functional and highly integrated devices, the company is also accelerating efforts to establish high-density interconnect technologies with high manufacturing complexity. We spoke with President & CEO Takahisa Amemiya about the evolving market environment and FICT's business outlook from fiscal year 2026 onward.

Q: How would you describe the current market conditions?
A-Takahisa Amemiya:
Business performance remains strong. Demand driven by AI applications is fueling a significant increase in orders for high-multilayer PCBs used in semiconductor testers and high-performance servers. In the high-performance server segment, we serve both major cloud service providers and emerging players, with 30- to 40-layer boards now forming the mainstream. In addition, we continue to maintain a high level of orders for probe cards, main boards for semiconductor test equipment, and ST (space transformer) products manufactured using SAP technology.

Q: You also provide contract processing for high-performance package substrates.
A-Takahisa Amemiya:
Yes. As part of our contract manufacturing business, we provide high-precision via formation and router processing for FC-BGA core substrates. The operating rate at our Kurohime Plant continues to rise, and the facility is operating at a high level of activity.

Q: What is your outlook for fiscal year 2026?
A-Takahisa Amemiya:
Supported by strong demand, we achieved approximately 20% year-on-year growth in both

revenue and profit in fiscal year 2025. Looking ahead to fiscal year 2026, we expect continued high growth, driven primarily by robust demand related to AI applications.
We will continue to accurately capture customer requirements for high layer counts and high density and respond proactively to those needs. While sourcing for certain materials has become more challenging, we are working closely with our production teams to maintain stable and reliable manufacturing operations.

Q: Your shareholder composition has also changed.

A-Takahisa Amemiya:

In February 2025, the private equity firm MBK Partners (MBKP) and FormFactor, Inc., a major probe card manufacturer, became our shareholders. MBK Partners holds an 80% stake, and FormFactor holds 20%. Under this new shareholder structure, we aim to further enhance FICT's corporate value.

Q: You have also opened new R&D bases. What is the objective?

A-Takahisa Amemiya:

With the emergence of next-generation high-speed and highly integrated devices, development of advanced packages, including 3D integration, is accelerating. At the same time, we are seeing growing demand for advanced interconnect technologies that support fine-pitch designs, such as space transformers (ST), larger package substrates, and redistribution layer (RDL) formation.
To address these trends, we have newly opened the Kawasaki Laboratory and the Itoshima Laboratory in Fukuoka Prefecture, establishing a three-location R&D structure together with our existing Nagano Laboratory. The Kawasaki Laboratory is primarily responsible for R&D strategy and planning, while the Nagano and Itoshima laboratories focus on fundamental research as well as the development and validation of prototyping processes.
In particular, the Itoshima Laboratory is located within the Fukuoka Highly Integrated Semiconductor Solution Center and is positioned as a development base for advanced 3D integration technologies, including glass substrates.

Q: You have also developed ultra-high-multilayer boards.

A-Takahisa Amemiya:

In recent years, the growing adoption of high-speed memory and related technologies has made ultra-high multilayer probe cards capable of supporting these applications increasingly essential. Ultra-high multilayer boards approaching 100 layers have already emerged, and demand for even higher layer counts is expected to continue.

In fact, by autumn 2025, we had completed the development of an ultra-high multilayer PCB featuring a board thickness of 10 mm and 160 layers. Using our proprietary All Layer (Z) Connection Structure (F-ALCS) technology process, multiple multilayer board blocks are pre-fabricated, after which the interlayer vias of each block are interconnected using conductive paste.

F-ALCS enables fine patterning down to **L/S 50 µm / 50 µm**, and because it does not generate via stubs, it is ideally suited for high-speed signal processing boards. Within this year, we plan to take on the challenge of developing **180-layer** boards.

Q: Please tell us about your approach to investment.

A-Takahisa Amemiya:

At our Nagano headquarters plant, we are focusing on eliminating bottlenecks in the SAP process to enable finer wiring. We are introducing automation wherever possible, including the deployment of AMRs (autonomous mobile robots), and have implemented semiconductor-grade countermeasures such as Class 100 cleanrooms to effectively control particulate contamination.

At our Kurohime Plant, which specializes in high-precision via formation, we are transitioning to highly efficient multi-axis mechanical drilling machines to further improve productivity.

In addition, expansion work is currently underway on the development lines at the Nagano headquarters plant to strengthen our next-generation development capabilities. The new facilities are scheduled to commence operations in fiscal year 2027, accompanied by an increase in staffing.

(Interviewer: Special Editorial Committee Member, Kazuhiro Nomura)

Source: Electronic Device Industry News (Japanese)
This English translation is published with permission.